

ABSTRACT OF THE DISCLOSURE

A lead-frame for semiconductor devices having a mold with at least one air vent for the resin to seep out of during its injecting into the mold, the air vent being positioned between the upper and lower surface of the frame, wherein the frame provides a through hole positioned at the outlet of the air vent so that, when the resin has solidified, it forms a flash which is in coherence with the surface of the frame.

D:\NrPortbl\iManage\SUSANH\198766_1.DOC